

ELECTROLESS NICKEL STRIKE PLATING SOLUTION AND
METHOD FOR FORMING NICKEL FILM

Abstract

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An object of the present invention is to provide an electroless nickel plating solution that can form a nickel film which can surely cover a surface of a copper material even when the film thickness is thin, and a
10 method for forming a nickel film using the electroless nickel plating solution. In order to solve the above-mentioned problems, the electroless nickel strike plating solution used for forming the nickel film on the surface of the copper material includes: a water-soluble nickel
15 salt in a concentration of 0.002 to 1 g/L in terms of nickel; one or more carboxylic acids or salts thereof; and one or more reducing agents selected from the group of dimethylamine borane, trimethylamine borane, hydrazine and hydrazine derivatives.

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[FIG. 1]